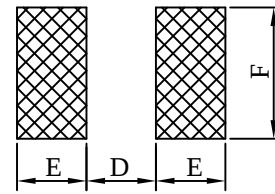
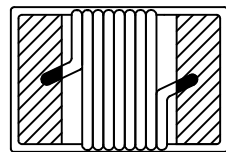
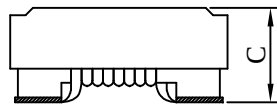
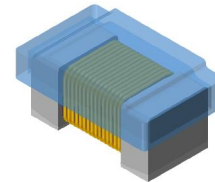
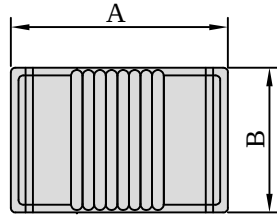


SPECIFICATION

REF. :

PROD. NAME	Wound Chip Inductor	ABC'S DWG NO.		ESW0805□□□□L□-□□□		
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I . Configuration and dimensions :



(PCB Pattern)

Unit : mm

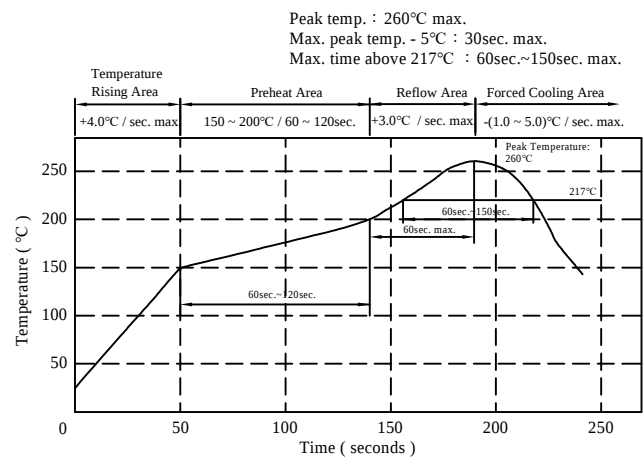
A	B	C	D	E	F
2.29 max.	1.73 max.	1.52 max.	0.76 typ.	1.02 typ.	1.78 typ.

II . Description :

- a . Body : Ceramic
- b . Enamelled copper wire : H class
- c . Product weight : 11 mg (ref.)
- d . Moisture sensitivity Level 1
- e . Products comply with RoHS' requirements
- f . Halogen free
- g . Recommended products should be used within 12 months from the date of delivery

III . General specification :

- a . Operating temp. : -40°C----+85°C
(Temp. rise included)
- b . Resistance to solder heat : 260°C.10 sec.



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SPECIFICATION

REF. :

PROD. NAME	Wound Chip Inductor	ABC'S DWG NO.		ESW0805□□□□L□-□□□		
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IV . Electrical characteristics :

DWG No.	Inductance (nH)	Tolerance	Q min.	Test Freq. (Hz)		SRF (MHz) min.	RDC (Ω) max.	Irms (mA) max.
				L	Q			
ESW08052N2□L□-□□□	2.2	S,J,K,M	50	250M	1.0G	7900	0.06	800
ESW08052N7□L□-□□□	2.7	S,J,K,M	50	250M	1.0G	7900	0.06	800
ESW08053N0□L□-□□□	3.0	S,J,K,M	40	250M	1.5G	7900	0.06	800
ESW08053N3□L□-□□□	3.3	S,J,K,M	40	250M	1.5G	7900	0.08	600
ESW08053N6□L□-□□□	3.6	S,J,K,M	20	250M	1.0G	7900	0.20	200
ESW08053N9□L□-□□□	3.9	S,J,K,M	20	250M	1.0G	7900	0.20	150
ESW08054N7□L□-□□□	4.7	S,J,K,M	35	250M	1.0G	6200	0.08	600
ESW08055N1□L□-□□□	5.1	S,J,K,M	50	250M	1.0G	6200	0.08	600
ESW08055N6□L□-□□□	5.6	J,K,M	65	250M	1.0G	5900	0.08	600
ESW08056N2□L□-□□□	6.2	J,K,M	65	250M	1.0G	5900	0.08	600
ESW08056N8□L□-□□□	6.8	J,K,M	50	250M	1.0G	5600	0.11	600
ESW08057N5□L□-□□□	7.5	J,K,M	50	250M	1.0G	4800	0.14	600
ESW08058N2□L□-□□□	8.2	J,K,M	50	250M	1.0G	4400	0.12	600
ESW08059N1□L□-□□□	9.1	J,K,M	60	250M	500M	4300	0.10	600
ESW080510N□L□-□□□	10.0	J,K,M	60	250M	500M	4300	0.10	600
ESW080512N□L□-□□□	12.0	J,K,M	50	250M	500M	4000	0.15	600
ESW080515N□L□-□□□	15.0	J,K,M	50	250M	500M	3200	0.17	600
ESW080516N□L□-□□□	16.0	J,K,M	50	250M	500M	3200	0.17	600
ESW080518N□L□-□□□	18.0	J,K,M	50	250M	500M	3100	0.20	600
ESW080520N□L□-□□□	20.0	J,K,M	55	250M	500M	2600	0.22	500
ESW080522N□L□-□□□	22.0	G,J,K,M	55	250M	500M	2600	0.22	500
ESW080523N□L□-□□□	23.0	G,J,K,M	50	250M	500M	2400	0.22	500
ESW080524N□L□-□□□	24.0	G,J,K,M	50	250M	500M	2400	0.22	500
ESW080525N□L□-□□□	25.0	G,J,K,M	50	250M	500M	2450	0.22	500
ESW080527N□L□-□□□	27.0	G,J,K,M	55	250M	500M	2580	0.25	500
ESW080530N□L□-□□□	30.0	G,J,K,M	55	250M	500M	2400	0.25	500
ESW080533N□L□-□□□	33.0	G,J,K,M	60	250M	500M	2150	0.27	500
ESW080536N□L□-□□□	36.0	G,J,K,M	55	250M	500M	1900	0.27	500
ESW080539N□L□-□□□	39.0	G,J,K,M	60	250M	500M	1850	0.29	500
ESW080543N□L□-□□□	43.0	G,J,K,M	60	200M	500M	1800	0.34	500
ESW080547N□L□-□□□	47.0	G,J,K,M	60	200M	500M	1700	0.31	500
ESW080550N□L□-□□□	50.0	G,J,K,M	60	200M	500M	1650	0.34	500
ESW080556N□L□-□□□	56.0	G,J,K,M	60	200M	500M	1600	0.34	500
ESW080562N□L□-□□□	62.0	G,J,K,M	60	200M	500M	1450	0.36	500
ESW080564N□L□-□□□	64.0	G,J,K,M	60	200M	500M	1500	0.38	500
ESW080568N□L□-□□□	68.0	G,J,K,M	60	200M	500M	1500	0.38	500
ESW080572N□L□-□□□	72.0	G,J,K,M	60	150M	500M	1400	0.38	500
ESW080575N□L□-□□□	75.0	G,J,K,M	60	150M	500M	1400	0.40	450
ESW080578N□L□-□□□	78.0	G,J,K,M	60	150M	500M	1400	0.40	450

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千如電子集團
ABC-ATEC ELECTRONICS GROUP

SPECIFICATION

REF. :

PROD. NAME	Wound Chip Inductor	ABC'S DWG NO.		ESW0805□□□□L□-□□□				
		REV.	20250318-A	PAGE	2-1			

DWG No.	Inductance (nH)	Tolerance	Q min.	Test Freq. (Hz)		SRF (MHz) min.	RDC (Ω) max.	Irms (mA) max.
				L	Q			
ESW080582N□L□-□□□	82.0	G,J,K,M	65	150M	500M	1330	0.42	400
ESW080591N□L□-□□□	91.0	G,J,K,M	65	150M	500M	1330	0.48	400
ESW0805R10□L□-□□□	100.0	G,J,K,M	65	150M	500M	1250	0.46	400
ESW0805R11□L□-□□□	110.0	G,J,K,M	50	150M	250M	1100	0.48	400
ESW0805R12□L□-□□□	120.0	G,J,K,M	50	150M	250M	1100	0.51	400
ESW0805R13□L□-□□□	130.0	G,J,K,M	50	100M	250M	920	0.56	400
ESW0805R14□L□-□□□	140.0	G,J,K,M	50	100M	250M	920	0.56	400
ESW0805R15□L□-□□□	150.0	G,J,K,M	50	100M	250M	920	0.56	400
ESW0805R16□L□-□□□	160.0	G,J,K,M	50	100M	250M	920	0.60	400
ESW0805R18□L□-□□□	180.0	G,J,K,M	50	100M	250M	920	0.64	400
ESW0805R20□L□-□□□	200.0	G,J,K,M	50	100M	250M	860	0.68	400
ESW0805R21□L□-□□□	210.0	G,J,K,M	50	100M	250M	820	0.70	400
ESW0805R22□L□-□□□	220.0	G,J,K,M	50	100M	250M	820	0.70	400
ESW0805R24□L□-□□□	240.0	G,J,K,M	44	100M	250M	770	1.00	350
ESW0805R25□L□-□□□	250.0	G,J,K,M	45	100M	250M	750	1.20	350
ESW0805R27□L□-□□□	270.0	G,J,K,M	48	100M	250M	730	1.00	350
ESW0805R28□L□-□□□	280.0	G,J,K,M	48	100M	250M	550	1.35	350
ESW0805R29□L□-□□□	290.0	G,J,K,M	48	150M	250M	450	1.40	310
ESW0805R30□L□-□□□	300.0	G,J,K,M	48	150M	250M	450	1.40	310
ESW0805R33□L□-□□□	330.0	G,J,K,M	48	100M	250M	650	1.40	310
ESW0805R36□L□-□□□	360.0	G,J,K,M	48	100M	250M	630	1.45	300
ESW0805R39□L□-□□□	390.0	G,J,K,M	48	100M	250M	600	1.50	290
ESW0805R42□L□-□□□	420.0	G,J,K,M	33	50M	100M	425	1.70	250
ESW0805R43□L□-□□□	430.0	G,J,K,M	33	50M	100M	425	1.70	250
ESW0805R47□L□-□□□	470.0	G,J,K,M	33	50M	100M	375	1.76	250
ESW0805R56□L□-□□□	560.0	G,J,K,M	23	25M	50M	330	1.90	230
ESW0805R62□L□-□□□	620.0	G,J,K,M	23	25M	50M	320	2.20	210
ESW0805R68□L□-□□□	680.0	G,J,K,M	23	25M	50M	310	2.20	190
ESW0805R75□L□-□□□	750.0	G,J,K,M	23	25M	50M	310	2.30	180
ESW0805R82□L□-□□□	820.0	G,J,K,M	23	25M	50M	310	2.35	180
ESW0805R88□L□-□□□	880.0	G,J,K,M	23	25M	50M	310	2.35	180
ESW0805R91□L□-□□□	910.0	G,J,K,M	22	25M	50M	250	2.45	170
ESW08051R0□L□-□□□	1000.0	J,K,M	20	25M	50M	220	2.50	170
ESW08051R2□L□-□□□	1200.0	J,K,M	20	25M	25M	180	2.90	150
ESW08051R5□L□-□□□	1500.0	J,K,M	20	25M	25M	160	3.30	150
ESW08051R6□L□-□□□	1600.0	J,K,M	20	25M	25M	140	3.40	150
ESW08051R8□L□-□□□	1800.0	J,K,M	20	25M	25M	130	3.50	120
ESW08052R2□L□-□□□	2200.0	J,K,M	20	25M	25M	100	4.50	120
ESW08052R7□L□-□□□	2700.0	J,K,M	18	25M	25M	80	4.80	100

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SPECIFICATION

REF. :

PROD. NAME	Wound Chip Inductor	ABC'S DWG NO.		ESW0805□□□□L□-□□□		
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DWG No.	Inductance (nH)	Tolerance	Q min.	Test Freq. (Hz)		SRF (MHz) min.	RDC (Ω) max.	Irms (mA) max.
				L	Q			
ESW08053R3□L□-□□□	3300.0	J,K,M	18	25M	25M	50	6.80	50
ESW08054R7□L□-□□□	4700.0	J,K,M	18	25M	25M	40	7.00	30

- 1). Electrical specifications at 25°C
- 2). Irms base on temp. rise 40°C max.
- 3). Tolerance : S(±0.3) 、 G(±2%) 、 J(±5%) 、 K(±10%) 、 M(±20%)

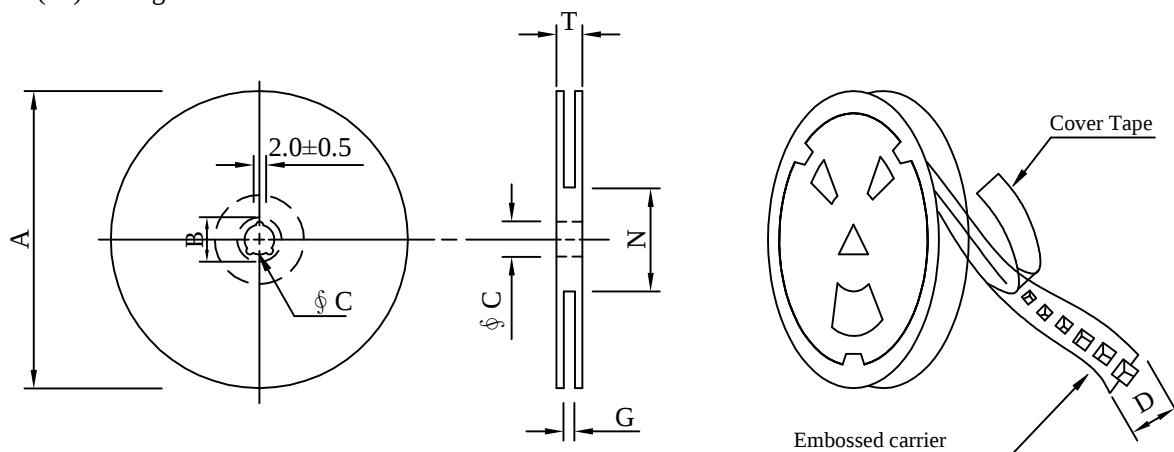
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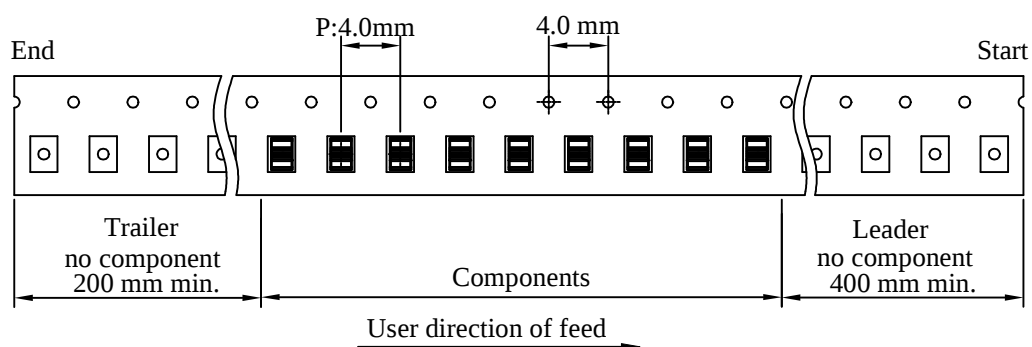
PROD. NAME	Wound Chip Inductor	ABC'S DWG NO.		ESW0805□□□□L□-□□□		
		REV.	20250318-A	PAGE	3	

V . Packaging information :

(1) Configuration



※Carrier tape width : D



(2) Dimensions

Unit:mm

Style	A	B	C	D	G	N	T
07 - 08	178	21	13	8	8.4	60	12.4

(3) Q'TY & G.W. Per package

Code	Inner : Reel			Outer : Carton		
	Q'TY (pcs)	G.W. (g)	Style	Q'TY (pcs)	G.W. (kg)	Size (cm)
B	2,000	110	07 - 08	100,000	7.0	42 x 41 x 24

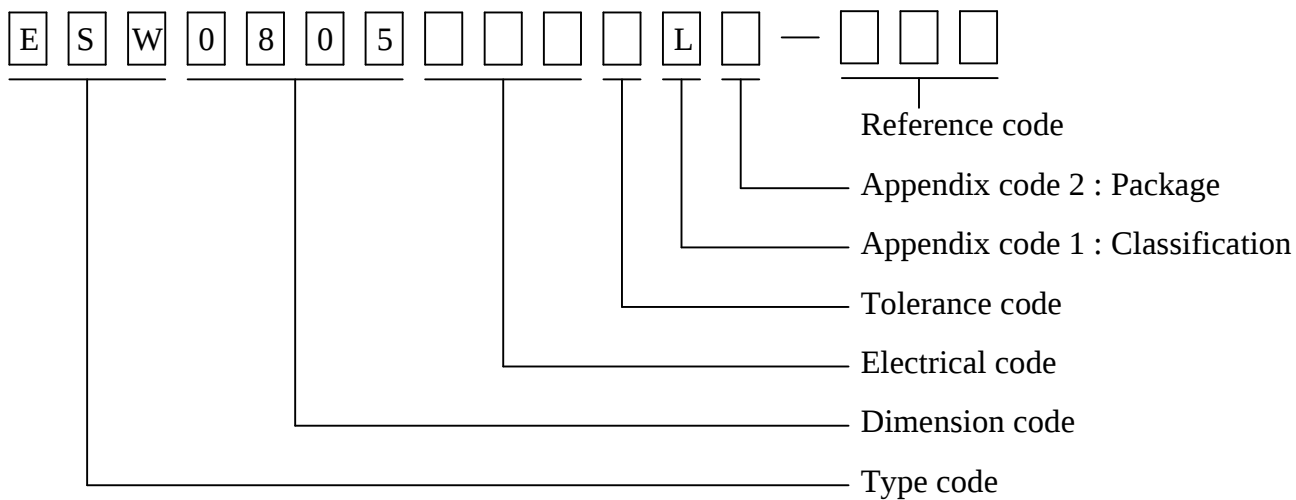
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SPECIFICATION

REF. :

PROD. NAME	Wound Chip Inductor	ABC'S DWG NO.		ESW0805□□□□L□-□□□		
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VI . Drawing number expression :



Appendix code 1 : Product Classification

Appendix code 2 : Package Information

Code	Inner package	Cover tape	Carrier tape	Bag	Package Q'TY	Remark
B	T /R (Reel package)	NA	NA	NA	2,000 pcs	

SPECIFICATION

REF. :

PROD. NAME	Wound Chip Inductor	ABC'S DWG NO.	ESW0805□□□□L□-□□□		
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VII . Reliability test :

Item	Reference documents	Test Condition	Test Specification
1.High Temperature Exposure	IES 68-2-2	1.Temperature:85±3°C 2.Time:96 hours.	1.No mechanical or electrical damage. 2.ΔL/L≤10% ΔQ/Q≤10%
2.Low Temperature Exposure	IES 68-2-1	1.Temperature: -40±3°C 2.Time:96 hours.	1.No mechanical or electrical damage. 2.ΔL/L≤10% ΔQ/Q≤10%
3.Temperature Cycling	IEC 68-2-14	1.Temperature: -40°C ~ +85°C 2.Number of cycle:100 cycle 3.Dwell time:30 minutes	1.No mechanical or electrical damage. 2.ΔL/L≤10% ΔQ/Q≤10%
4.Biased Humidity Test	IEC 68-2-3	1.Temperature : 60±3 °C 2.Humidity: 90%~95% RH. 3.Time:96 Hours	1.No mechanical or electrical damage. 2.ΔL/L≤10% ΔQ/Q≤10%
5.External Visual	JESD22-B 101 & MIL-STD-883 Method 2009	Inspect product constructions, marking and workmanship.	1.No pollution on the surface of products. 2.No crack.
6.Physical Dimensions	JESD22-B 100	Verify physical dimensions to the applicable product detail specification.	Per product specification standard
7.Vibration Test	IEC 68-2-6	1.Frequency :10-55-10 Hz 2.Amplitude : 1.5 mm 3.Direction : X , Y , Z 4.Duration : 2HRS/X,Y,Z	1.No mechanical or electrical damage. 2.ΔL/L≤10% ΔQ/Q≤10%
8.Resistance To Soldering Heat Test	IEC 68-2-20	1.Highest temperature : 260 °C 2.Time (temp.≥ 217°C) : 60~150 Second. 3.Reflow times : 2 times.	1.No mechanical or electrical damage. 2.ΔL/L≤10% ΔQ/Q≤10%
9.Temperature Rise Current	JIS C 6436 & User SPEC.	1.Applied rated current for 10 minutes. 2.Temperature measure by digital surface thermometer. 3.Irms current :	Surface temperature rise is less than 40°C max
10.Solderability Test	IEC 68-2-20	1.Baking in pre-testing : 150±5°C / 16Hours±30 min. 2. Dip pads in flux then dip in solder pot at 245°C±5°C for 3±0.5 seconds.	More than 95% soldering coverage min on terminations.
11.Electrical Characteriazation	MIL-STD-202 Method 304 & User SPEC.	1.Operating temperature : -40°C~85°C 2.Room temperature : 25°C.	1.No mechanical or electrical damage. 2.ΔL/L≤10% ΔQ/Q≤10%
12.Drop	IEC 68-2-32	1.Products shall be mounted on SPEC. PCB and dropped down from a height of 100 cm 2.Drop total time : 6 time (Every side of sample drop 2 time)	1.No mechanical or electrical damage. 2.ΔL/L≤10% ΔQ/Q≤10%
13.Board Flex	IEC 68-2-21	1.Amount of deflection : 2 mm 2.Direction for test : Bottom of PCB 3.Holding time : 60 sec.	After test, inductors shall be no mechanical damage.
14.Terminal Strength Test	IEC 68-2-21	1.Apply push force to samples mounted on PCB. 2.Force of 2kg for 30±1 seconds.	After test, inductors shall be no mechanical damage.

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SPECIFICATION

REF. :

PROD. NAME	Wound Chip Inductor	ABC'S DWG NO.	ESW0805□□□□L□-□□□		
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VIII . Safety notes :

1. The risks of using the product are highly relevant to the field of application and need to be evaluated by both user and manufacturer. If the product is used for a purpose that directly affects personal safety or will cause significant impact or loss to the society , please be sure to contact us first for confirmation.
產品使用的風險與應用領域有高度相關，若您應用於直接影響人身安全系統或對社會會造成重大影響與損失之相關用途，請務必優先與我們聯繫確認。
2. The storage period is less than 12 months. Ensure to follow the storage conditions (Temperature: 5 to 30°C, Humidity: 10 to 60% RH or less). If the storage time is exceeded the limit, the electrodes might be deteriorate of terminal soldering.
儲存期不超過12個月，務必遵守儲存條件（溫度：5至30°C，濕度：10至60%RH以下）。如果超過了儲存時間，端子電極可能會氧化而影響焊接。
3. Do not use or store in locations where there are conditions such as gas corrosion (salt, acid, alkali, etc.).
不要在有氣體腐蝕等條件的地方使用或存放（鹽，酸，鹼等）。
4. Soldering corrections after mounting should be within the range of the conditions determined in the specifications. If overheated, a short circuit, performance deterioration, or lifespan shortening may occur.
安裝時的焊接條件應在規格範圍內。如果超過要求，可能會發生短路，性能下降或壽命縮短。
5. When using, it should try to avoid excessive mechanical impact on the product, such as collision / drop ... and other reasons.
使用時，應盡量避免產品受到過度機械衝擊，如碰撞/掉落...等原因。
6. When embedding a printed circuit board where a chip is mounted to a set, be sure that residual stress is not given to the chip due to the overall distortion of the printed circuit board and partial distortion such as at screw tightening portions.
將已安裝新片的電路板組裝到裝置時，請注意應盡量避免電路板受到組裝變形...等，導致產品受到應力。
7. Self heating (temperature increase) occurs when the power is turned ON, so the tolerance should be sufficient for the set thermal design.
產品會因通電而自我發熱(溫度上升)，因此在熱影響設計方面，需保留適當公差。
8. Do not expose the products to magnets or magnetic fields.
請勿將產品暴露於磁鐵或是磁場中。
9. If you would like to use this products to performance and/or quality require a more stringent level of safety or reliability, or whose failure, malfunction or trouble could cause serious damage to society, person or property, or if you have special requirements exceeding the range or conditions set forth in the each catalog, please contact us.
如果您希望將此產品用於性能和/或質量要求更嚴格的安全性或可靠性，或其失敗、故障或麻煩可能對社會、個人或財產造成嚴重損害，或者您有特殊情況要求超出目錄中規定的範圍或條件，請與我們聯繫。